

8 7 6 5 4 3 2 1

ENG. NO.:

EDP NO.:

SIMILAR ITEM

CADFILE NO.:

DO NOT SCALE DRAWING

F

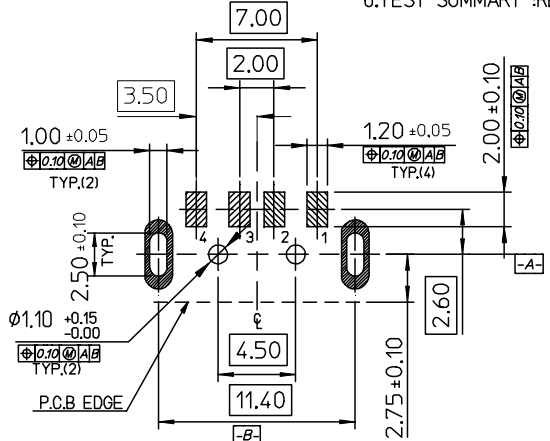
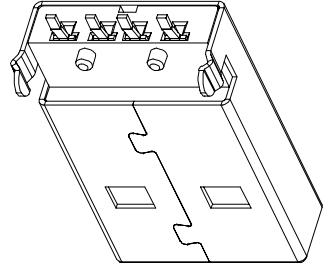
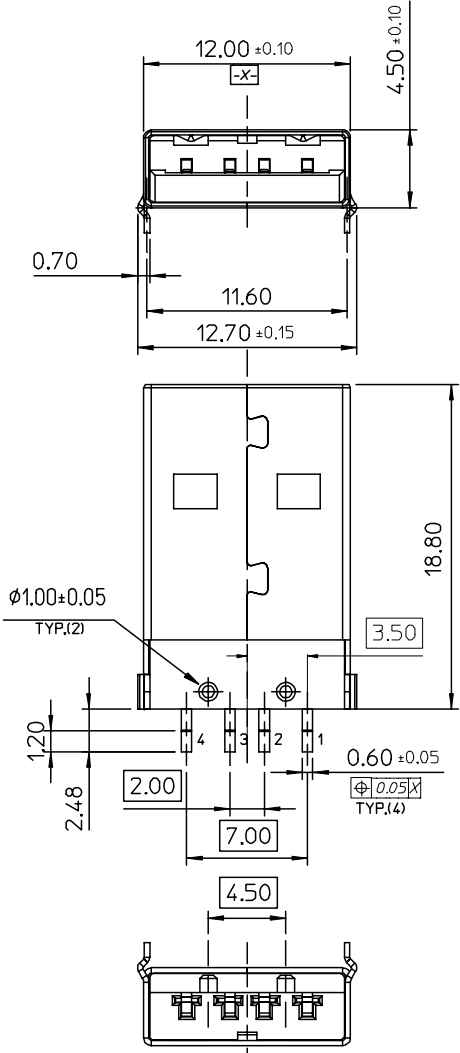
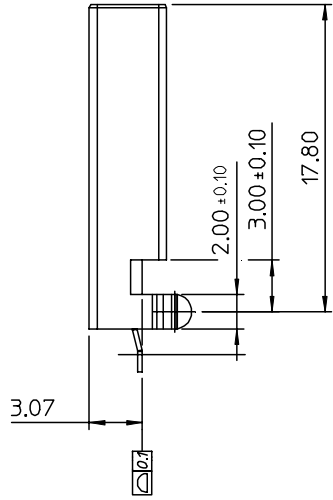
E

D

C

B

A



RECOMMENDED PCB LAYOUT

NOTES:

- 1.MATERIAL:
SHELL: SPCC
HOUSING: THERMOPLASTIC, GLASS FIBER FILLED,
UL 94V-0 RATED.COLOR BLACK.
CONTACT: BRASS
- 2.PLATING:
TERMINAL:
CONTACT AREA:GOLD(Au)
THICKNESS=30 MICROINCH MINIMUM.
SOLDER TAIL:TIN(Sn), ALLOY,
THICKNESS=120 MICROINCH MINIMUM.
UNDER PLATED:NICKEL(NI),THICKNESS=50 MICROINCH MINIMUM.
METAL SHELL:
NICKEL(NI),THICKNESS=120 MICROINCH MINIMUM.
UNDER PLATE: COPPER(Cu), THICKNESS=50 MICROINCH MINIMUM.
- 3.RECOMMENDED PCB THICKNESS:1.20~1.60mm
- 4.PRODUCT SPECIFICATION:REFER TO PS-48037-001
- 5.PACKAGE SPECIFICATION:SEE TABLE
- 6.TEST SUMMARY :REFER TO TS-48037-001

48037-2000	T&R	PK-48037-200	
48037-1000	TRAY	PK-48037-001	
MOLEX P/N	PACKAGE	PACKAGE SPEC.	REMARK

THIRD ANGLE PROJECTION	DIMENSIONS:			SHT	REV
	<input type="checkbox"/> mm	<input type="checkbox"/> INCH	<input checked="" type="checkbox"/> mm	<input type="checkbox"/> ONLY	REVISE ON CAD ONLY

C	ADD NEW P/N AND UPDATE PLATING SPEC. EC NO.SH2005-0163 DRWN: KEVIN CHANG CHK: KEVIN CHANG APPR:
	RTM EC NO.T2004-0067 DRWN: KEVIN CHANG CHK: SAM SHIN APPR:ERICK LAN
B	
REV	DESCRIPTION

QUALITY SYMBOLS	MAJOR	MINOR
	▲	▽
	+0	-0
	CRITICAL	
	∇	
	+0	-0

GENERAL TOLERANCES: (UNLESS SPECIFIED)	SCALE	DESIGN UNITS
4 PLACES \ . \ .	mm	mm
3 PLACES \ . \ .	INCH	INCH
2 PLACES ±0.25 ±0.010		
1 PLACE ±0.25 ±0.010		
ANGULAR: ±3°		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

DRAWN BY & DATE COLIN DUAN 030822	CAD FILENAME S4803702.MI
CHECKED BY & DATE SAM SHIN 030822	MATERIAL NO. SEE TABLE
APPROVED BY & DATE WILSON CHANG 030822	DRAWING NO. SD-48037-002

TITLE: USB A TYPE PLUG R/A CONNECTOR(SMT)		SHEET NO. 1 OF 1
MOLEX INCORPORATED		SIZE A3
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